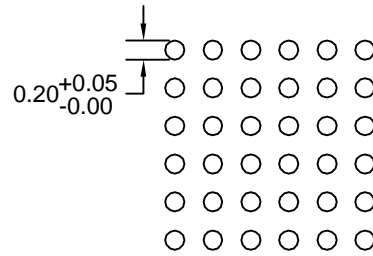
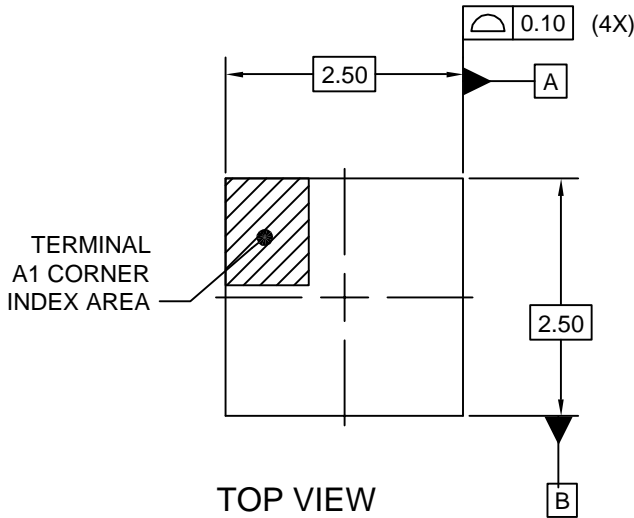
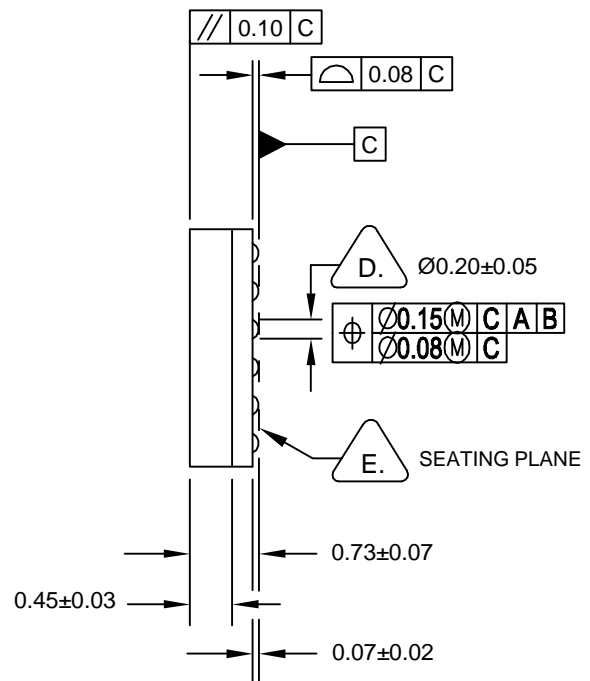
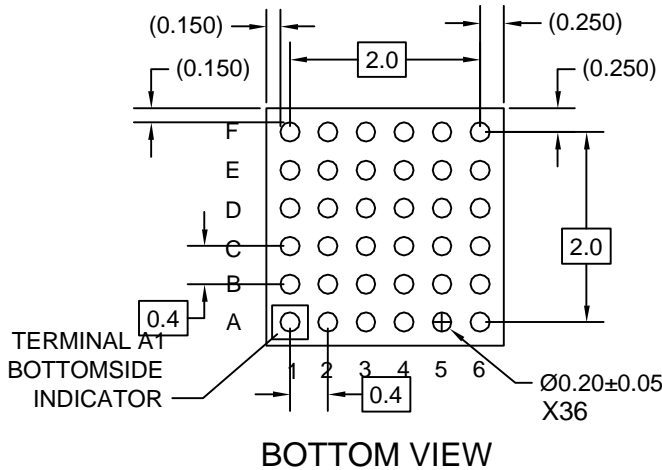


REVISIONS				
LTR	DESCRIPTION	EDCN	DATE	BY/APP'D
1	NEW DRAWING	ECN-MKT-BGA36R1	14/09/2006	H.ALLEN
2	rev'd ball size	ECN-MKT-BGA36R2	1/11/2006	H.ALLEN
3	rev'd ball X dim and title	ECN-MKT-BGA36R3	12/12/2006	H.ALLEN



LAND PATTERN
RECOMMENDATION



NOTES:

- A. NO CURRENT JEDEC REGISTRATION
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994
- DIMENSION IS MEASURED AT THE MAXIMUM SOLDER BUMP DIAMETER, PARALLEL TO PRIMARY DATUM C.
- PRIMARY DATUM C AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BUMPS.
- F. LAND PATTERN RECOMMENDATION PER IPC-7351 TABLE 14-15
LAND PATTERN NAME PER TABLE 3-15: BGA40P+6X7-42
- G. THE BASIC METAL LANDPATTERN GRID PITCH IS 0.40mm.
- H. THE DRAWING FILENAME AND REV IS BGA36rev3

BGA36rev3

APPROVALS	DATE	FAIRCHILD SEMICONDUCTOR		82 RUNNING HILL RD. SOUTH PORTLAND, ME. 04106	
DRAWN A. Arcadera	12/12/2006	36BALL, UTSBGA, NON-JEDEC, .4MM PITCH, 2.5MM SQUARE			
DFTS. CHK H.ALLEN	12/12/2006				
ENGR. CHK					
		SCALE N/A	SIZE N/A	DRAWING NUMBER MKT-BGA36A	REV 3
		DO NOT SCALE DRAWING		SHEET 1 of 1	